

JP 680 U.S. PTO
10/075293
02/15/02

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10075293	02/15/2002	287	758	287	VIKI TRINH

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**CONTINUING DATA VERIFIED:

No

** FOREIGN APPLICATIONS VERIFIED:

TAIWAN 00113355 02/11/2001

yes

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no	ATTORNEY DOCKET NO
35 USC 119 conditions met	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no	YEHC3010/EM
Verified and Acknowledged Examiners's initials	WZ 11/29/02	
TITLE : Method of reducing thick film stress of spin-on dielectric and the resulting sandwich dielectric structure		

U.S. DEPT. OF COMM/PAT & TM-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for 0.8
Assistant Examiner		DRAWING	
ISSUE FEE		Sheets Drwg.	Figs.Drwg.
Amount Due	Date Paid	Print Fig.	
Primary Examiner		Application Examiner	
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